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EIA STANDARD

Ceramic Dielectric Capacitors Classes I, II, III and IV – Part I: Characteristics and Requirements

EIA-198-1-F

(Revision of EIA-198-1-E)

NOVEMBER 2002



Electronic Components, Assemblies & Materials Association

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(From Standards Proposal No. 4979, formulated under the cognizance of the ECA P-2.1 Ceramic Dielectric Capacitors Subcommittee.)

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Ceramic Dielectric Capacitors Classes I, II, III, and IV

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Spec # /rev.	Description of changes	Pages	Date
EIA-198-F	Changed "Forward" to include reference to EIA-198-E	i	4/15/02
EIA-198-F	Changed "Clarification Statement" to include reference to EIA-198-E	i	4/15/02
EIA-198-F	Changed 1.1.2 Added Temperature Characteristics A through S, changed capacitor measurement period from 10hours to 24 hour	1	4/15/02
EIA-198-F	Changed 1.2.1 paragraph 4 on wave soldering large and small chip sizes	2	4/15/02
EIA-198-F	Added plate type to 1.2.3	2	4/15/02
EIA-198-F	Changed 1.3.1 title only	2	4/15/02
EIA-198-F	Added notes 1 and 2 to Table 1	3	4/15/02
EIA-198-F	Added explicit title and formatted table 4 to improve clarity.	5	4/15/02
EIA-198-F	Fixed format of table 4 and added note 2	5	4/15/02
EIA-198-F	Fixed format of table 5, added alpha code A	6	4/15/02
EIA-198-F	Removed numeric codes 4-8 in table 6	6	4/15/02
EIA-198-F	Changed Title to Leaded, Encapsulated Devices (Multilayer, Plate, Disk, Tubular) section 2.1	6	4/15/02
EIA-198-F	Added exception "8" to section 2.2 paragraph 2	7	4/15/02
EIA-198-F	Changed Table 7 name to include "Encapsulated"	8	4/15/02
EIA-198-F	Fixed format of table 8.	8	4/15/02
EIA-198-F	Changed title and paragraph 1 in 3.1 and fixed formatting of 3.1.1, 3.1.2	9	4/15/02
EIA-198-F	Changed method typo error on VTC from 103 to 105	10	4/15/02
EIA-198-F	Moved Damp Heat from 3.1.4 to section 3.1.2	10	4/15/02
EIA-198-F	Changed Test Requirements for most tests to reference Per Individual specification sheet since conditions are specifically defined in test methods Section 198-2	10-11	4/15/02

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